


PRODUCT / PROCESS CHANGE NOTIFICATION

1. PCN basic data

1.1 Company		STMicroelectronics International N.V
1.2 PCN No.	ADG/19/11527	
1.3 Title of PCN	Mold compound replacement for TO220	
1.4 Product Category	STPSxxx, STPSCxxx, STTHxxx, ACSxxx, ACSTxxx, BTBxxx, FERDxxx, TNxxx, TSxxx, TYNxxx series.	
1.5 Issue date	2019-05-01	

2. PCN Team

2.1 Contact supplier	
2.1.1 Name	FRANK SCHIFANO
2.1.2 Phone	+1 5148333778
2.1.3 Email	frank.schifano@st.com
2.2 Change responsibility	
2.2.1 Product Manager	Richard RENARD
2.1.2 Marketing Manager	Philippe LEGER
2.1.3 Quality Manager	Jean-Paul REBRASSE

3. Change

3.1 Category	3.2 Type of change	3.3 Manufacturing Location
Materials	New direct material part number (same supplier, different supplier or new supplier), Mold compound	ST assy site in China (STS) and subco in Asia (TFME/PSI)

4. Description of change

	Old	New
4.1 Description	Samsung SDI product termination.	Replacement of current mold compounds with alternative material. please refer to document 11478.
4.2 Anticipated Impact on form,fit, function, quality, reliability or processability?	no	

5. Reason / motivation for change

5.1 Motivation	Product discontinuance from current supplier.
5.2 Customer Benefit	SERVICE CONTINUITY

6. Marking of parts / traceability of change

6.1 Description	internal codification and QA number
------------------------	-------------------------------------

7. Timing / schedule

7.1 Date of qualification results	2019-08-29
7.2 Intended start of delivery	2019-09-13
7.3 Qualification sample available?	Upon Request

8. Qualification / Validation

8.1 Description			
8.2 Qualification report and qualification results	In progress	Issue Date	

9. Attachments (additional documentations)

11527 Public product.pdf
11527 PCN-TO220 industrial draft.pdf

10. Affected parts

10. 1 Current		10.2 New (if applicable)
10.1.1 Customer Part No	10.1.2 Supplier Part No	10.1.2 Supplier Part No
	STPS30L30CT	

IMPORTANT NOTICE – PLEASE READ CAREFULLY

Subject to any contractual arrangement in force with you or to any industry standard implemented by us, STMicroelectronics NV and its subsidiaries (“ST”) reserve the right to make changes, corrections, enhancements, modifications, and improvements to ST products and/or to this document at any time without notice. Purchasers should obtain the latest relevant information on ST products before placing orders. ST products are sold pursuant to ST’s terms and conditions of sale in place at the time of order acknowledgement.

Purchasers are solely responsible for the choice, selection, and use of ST products and ST assumes no liability for application assistance or the design of Purchasers’ products.

No license, express or implied, to any intellectual property right is granted by ST herein.

Resale of ST products with provisions different from the information set forth herein shall void any warranty granted by ST for such product.

ST and the ST logo are trademarks of ST. All other product or service names are the property of their respective owners.

Information in this document supersedes and replaces information previously supplied in any prior versions of this document.

© 2018 STMicroelectronics – All rights reserved